

IN THE ABSTRACT OF THE DISCLOSURE:

~~The present invention relates to a circuit board use member which uses a flexible film having a highly precise circuit pattern, a method for forming a circuit board composed of a flexible film having a highly precise circuit pattern, and an apparatus for forming the same.~~

~~That is, the present invention relates to a~~ A circuit board-use member ~~having~~ has a reinforcing plate, a removable organic layer, a flexible film having ~~at least one~~ a circuit pattern ~~on at least one of two surfaces~~, and a peeling-assist layer laminated in that order;

a method ~~for forming~~ forms a circuit board by ~~the steps of~~ forming a circuit pattern on ~~a surface of~~ a flexible film which is adhered to a reinforcing plate with a removable organic layer interposed therebetween, ~~the surface being opposite to that adhered to the reinforcing plate~~, and ~~[[then]]~~ peeling the flexible film, ~~in which the flexible film is peeled away from the reinforcing plate while a peel at an angle is maintained in the range of~~ ranging from more than 0° to 80°; and

an apparatus for forming a circuit board ~~by peeling a flexible film from a flexible film substrate formed of a reinforcing plate and the flexible film which is provided with a circuit pattern and~~

~~which is adhered to the reinforcing plate, the method having~~ has  
one of ~~the following means:~~ ~~i)~~ a separation means for separating  
the flexible film from the reinforcing plate while the ~~flexible~~  
film ~~is being in contact with~~ contacts a curved support body;  
[[ii)]] a curved separation means for separating the reinforcing  
plate from a support body for the flexible film while the  
~~reinforcing~~ plate is [[being]] curved; ~~and iii)~~ or a moving means  
for relatively moving holding means and peeling means, ~~the holding~~  
~~means for holding a circuit board use member, the peeling means~~  
having a wedge-shaped ~~peeling~~ member for peeling the flexible film.

~~The circuit board of the present invention can be preferably~~  
~~used for wiring boards for electronic devices, interposers for IC~~  
~~packaging, wiring boards for wafer level burn-in socket, and the~~  
~~like.~~